

ABSTRACT

The invention provides a polishing system and method for polishing or planarizing a substrate. The polishing system comprises (i) a liquid carrier, (ii) ammonium oxalate, (iii) a hydroxy coupling agent, and (iv) a polishing pad and/or an abrasive. The polishing method comprises contacting at least a portion of a substrate with the polishing system and polishing the portion of the substrate therewith.

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